



Material Content Data Sheet



Sales Product Name	BCP 56-16 H6327			Issued		8. September 2019		
MA#	MA001201208							
Package	PG-SOT223-4-24			Weight*		107.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003	0.00		26	
	noble metal	gold	7440-57-5	0.011	0.01		99	
	inorganic material	silicon	7440-21-3	0.129	0.12	0.13	1208	1333
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		80	
	non noble metal	titanium	7440-32-6	0.043	0.04		398	
	non noble metal	chromium	7440-47-3	0.128	0.12		1193	
	non noble metal	copper	7440-50-8	42.459	39.62	39.79	396160	397831
wire	non noble metal	copper	7440-50-8	0.078	0.07	0.07	725	725
encapsulation	organic material	carbon black	1333-86-4	0.624	0.58		5818	
	plastics	epoxy resin	-	9.354	8.73		87275	
	inorganic material	silicondioxide	60676-86-0	52.382	48.87	58.18	488742	581835
leadfinish	non noble metal	tin	7440-31-5	1.464	1.37	1.37	13660	13660
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4616	4616
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com